



**THE DATASHEET OF
NVMD3P03R2G**



NTMD3P03, NVMD3P03

MOSFET – Power, Dual, P-Channel, SOIC-8 -3.05 A, -30 V



ON Semiconductor®

<http://onsemi.com>

Features

- High Efficiency Components in a Dual SOIC-8 Package
- High Density Power MOSFET with Low $R_{DS(on)}$
- Miniature SOIC-8 Surface Mount Package – Saves Board Space
- Diode Exhibits High Speed with Soft Recovery
- I_{DSS} Specified at Elevated Temperature
- Avalanche Energy Specified
- Mounting Information for the SOIC-8 Package is Provided
- AEC-Q101 Qualified – NVMD3P03R2G
- These Devices are Pb-Free and are RoHS Compliant

Applications

- DC-DC Converters
- Low Voltage Motor Control
- Power Management in Portable and Battery-Powered Products, i.e.:
Computers, Printers, PCMCIA Cards, Cellular & Cordless Telephones

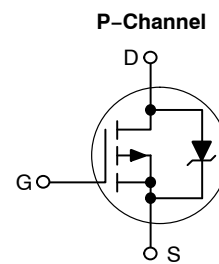
MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DSS}	-30	V
Gate-to-Source Voltage – Continuous	V_{GS}	± 20	V
Thermal Resistance – Junction-to-Ambient (Note 1)	$R_{\theta JA}$	171	$^\circ\text{C}/\text{W}$
Total Power Dissipation @ $T_A = 25^\circ\text{C}$	P_D	0.73	W
Continuous Drain Current @ 25°C	I_D	-2.34	A
Continuous Drain Current @ 70°C	I_D	-1.87	A
Pulsed Drain Current (Note 4)	I_{DM}	-8.0	A
Thermal Resistance – Junction-to-Ambient (Note 2)	$R_{\theta JA}$	100	$^\circ\text{C}/\text{W}$
Total Power Dissipation @ $T_A = 25^\circ\text{C}$	P_D	1.25	W
Continuous Drain Current @ 25°C	I_D	-3.05	A
Continuous Drain Current @ 70°C	I_D	-2.44	A
Pulsed Drain Current (Note 4)	I_{DM}	-12	A
Thermal Resistance – Junction-to-Ambient (Note 3)	$R_{\theta JA}$	62.5	$^\circ\text{C}/\text{W}$
Total Power Dissipation @ $T_A = 25^\circ\text{C}$	P_D	2.0	W
Continuous Drain Current @ 25°C	I_D	-3.86	A
Continuous Drain Current @ 70°C	I_D	-3.1	A
Pulsed Drain Current (Note 4)	I_{DM}	-15	A
Operating and Storage Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$
Single Pulse Drain-to-Source Avalanche Energy – Starting $T_J = 25^\circ\text{C}$ ($V_{DD} = -30$ Vdc, $V_{GS} = -4.5$ Vdc, Peak I_L $= -7.5$ Apk, $L = 5$ mH, $R_G = 25$ Ω)	E_{AS}	140	mJ
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	T_L	260	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Minimum FR-4 or G-10 PCB, $t =$ Steady State.
2. Mounted onto a 2" square FR-4 Board (1 in sq, 2 oz Cu 0.06" thick single sided), $t =$ steady state.

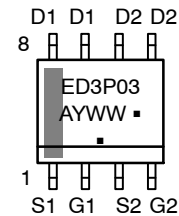
V_{DSS}	$R_{DS(on)}$ Typ	I_D Max
-30 V	85 m Ω @ -10 V	-3.05 A



MARKING DIAGRAM* AND PIN ASSIGNMENT



SOIC-8
SUFFIX NB
CASE 751
STYLE 11



ED3P03= Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

Device	Package	Shipping†
NTMD3P03R2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
NVMD3P03R2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D

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3. Mounted onto a 2" square FR-4 Board (1 in sq, 2 oz Cu 0.06" thick single sided), $t \leq 10$ seconds.
4. Pulse Test: Pulse Width = 300 μ s, Duty Cycle = 2%.

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ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted) (Note 5)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Drain-to-Source Breakdown Voltage ($V_{GS} = 0\text{ Vdc}$, $I_D = -250\ \mu\text{Adc}$) Temperature Coefficient (Positive)	$V_{(BR)DSS}$	-30 -	- -30	- -	Vdc mV/ $^\circ\text{C}$
Zero Gate Voltage Drain Current ($V_{DS} = -24\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$, $T_J = 25^\circ\text{C}$) ($V_{DS} = -24\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$, $T_J = 125^\circ\text{C}$) ($V_{DS} = -30\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$, $T_J = 25^\circ\text{C}$)	I_{DSS}	- - -	- - -	-1.0 -20 -2.0	μAdc
Gate-Body Leakage Current ($V_{GS} = -20\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$)	I_{GSS}	-	-	-100	nAdc
Gate-Body Leakage Current ($V_{GS} = +20\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$)	I_{GSS}	-	-	100	nAdc

ON CHARACTERISTICS

Gate Threshold Voltage ($V_{DS} = V_{GS}$, $I_D = -250\ \mu\text{Adc}$) Temperature Coefficient (Negative)	$V_{GS(th)}$	-1.0 -	-1.7 3.6	-2.5 -	Vdc
Static Drain-to-Source On-State Resistance ($V_{GS} = -10\text{ Vdc}$, $I_D = -3.05\text{ Adc}$) ($V_{GS} = -4.5\text{ Vdc}$, $I_D = -1.5\text{ Adc}$)	$R_{DS(on)}$	- -	0.063 0.090	0.085 0.125	Ω
Forward Transconductance ($V_{DS} = -15\text{ Vdc}$, $I_D = -3.05\text{ Adc}$)	g_{FS}	-	5.0	-	Mhos

DYNAMIC CHARACTERISTICS

Input Capacitance	$(V_{DS} = -24\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$, $f = 1.0\text{ MHz}$)	C_{iss}	-	520	750	pF
Output Capacitance		C_{oss}	-	170	325	
Reverse Transfer Capacitance		C_{rss}	-	70	135	

SWITCHING CHARACTERISTICS (Notes 6 and 7)

Turn-On Delay Time	$(V_{DD} = -24\text{ Vdc}$, $I_D = -3.05\text{ Adc}$, $V_{GS} = -10\text{ Vdc}$, $R_G = 6.0\ \Omega$)	$t_{d(on)}$	-	12	22	ns
Rise Time		t_r	-	16	30	
Turn-Off Delay Time		$t_{d(off)}$	-	45	80	
Fall Time		t_f	-	45	80	
Turn-On Delay Time	$(V_{DD} = -24\text{ Vdc}$, $I_D = -1.5\text{ Adc}$, $V_{GS} = -4.5\text{ Vdc}$, $R_G = 6.0\ \Omega$)	$t_{d(on)}$	-	16	-	ns
Rise Time		t_r	-	42	-	
Turn-Off Delay Time		$t_{d(off)}$	-	32	-	
Fall Time		t_f	-	35	-	
Total Gate Charge	$(V_{DS} = -24\text{ Vdc}$, $V_{GS} = -10\text{ Vdc}$, $I_D = -3.05\text{ Adc}$)	Q_{tot}	-	16	25	nC
Gate-Source Charge		Q_{gs}	-	2.0	-	
Gate-Drain Charge		Q_{gd}	-	4.5	-	

BODY-DRAIN DIODE RATINGS (Note 6)

Diode Forward On-Voltage	$(I_S = -3.05\text{ Adc}$, $V_{GS} = 0\text{ V}$) $(I_S = -3.05\text{ Adc}$, $V_{GS} = 0\text{ V}$, $T_J = 125^\circ\text{C}$)	V_{SD}	- -	-0.96 -0.78	-1.25 -	Vdc
Reverse Recovery Time	$(I_S = -3.05\text{ Adc}$, $V_{GS} = 0\text{ Vdc}$, $dI_S/dt = 100\text{ A}/\mu\text{s}$)	t_{rr}	-	34	-	ns
		t_a	-	18	-	
		t_b	-	16	-	
Reverse Recovery Stored Charge		Q_{RR}	-	0.03	-	μC

5. Handling precautions to protect against electrostatic discharge is mandatory.
6. Indicates Pulse Test: Pulse Width = 300 μs max, Duty Cycle = 2%.
7. Switching characteristics are independent of operating junction temperature.

TYPICAL ELECTRICAL CHARACTERISTICS

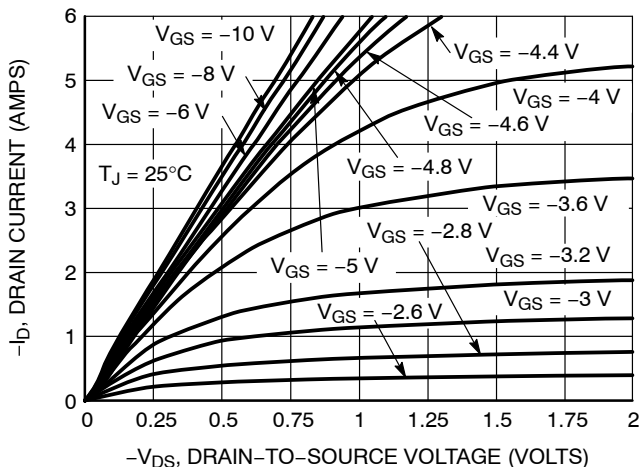


Figure 1. On-Region Characteristics

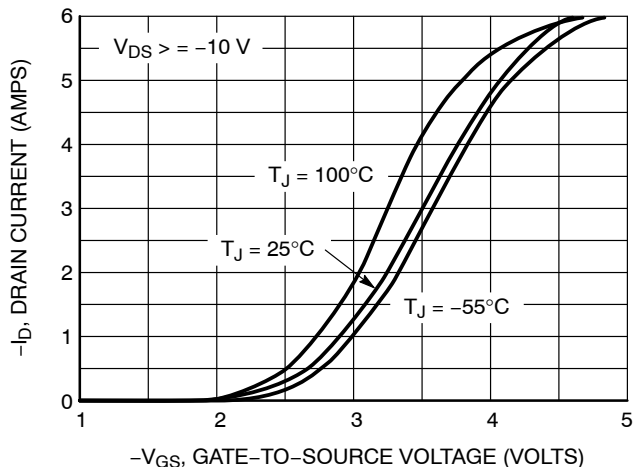


Figure 2. Transfer Characteristics

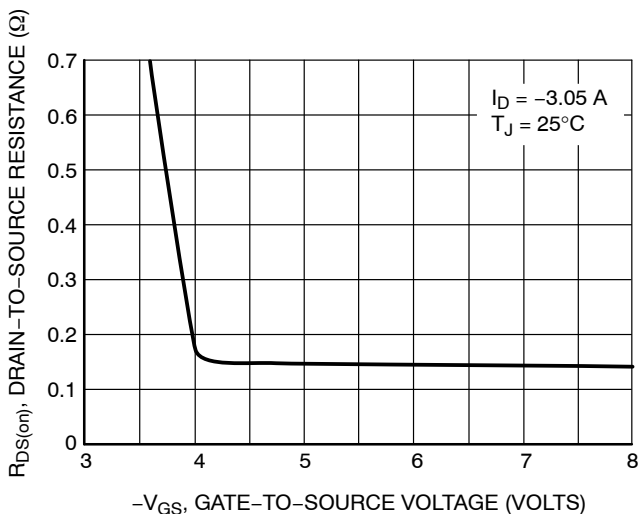


Figure 3. On-Resistance vs. Gate-to-Source Voltage

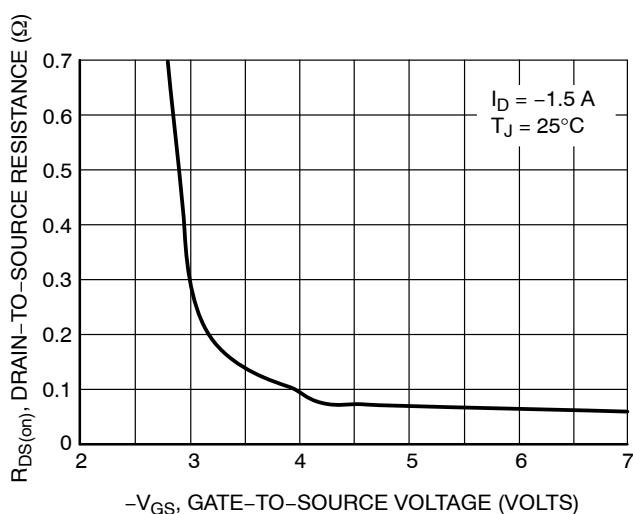


Figure 4. On-Resistance vs. Gate-to-Source Voltage

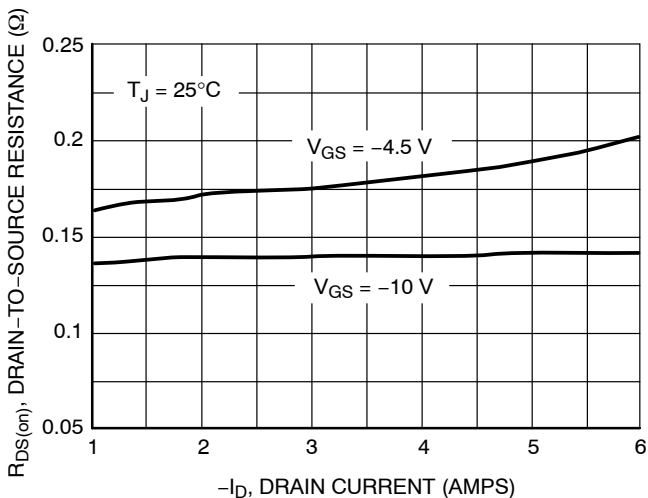


Figure 5. On-Resistance vs. Drain Current and Gate Voltage

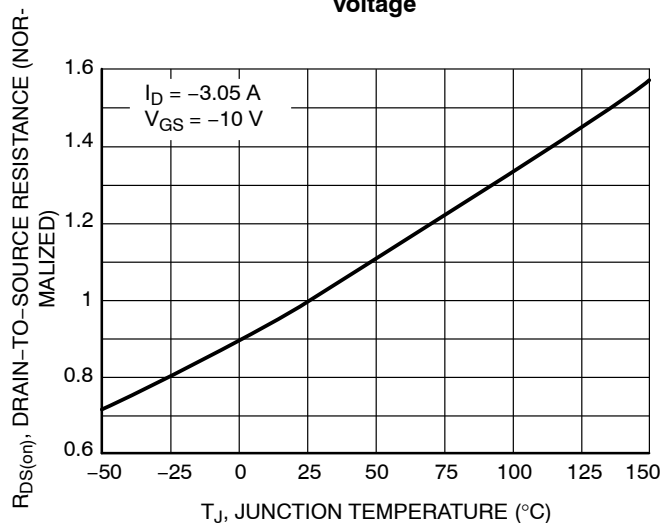


Figure 6. On Resistance Variation with Temperature

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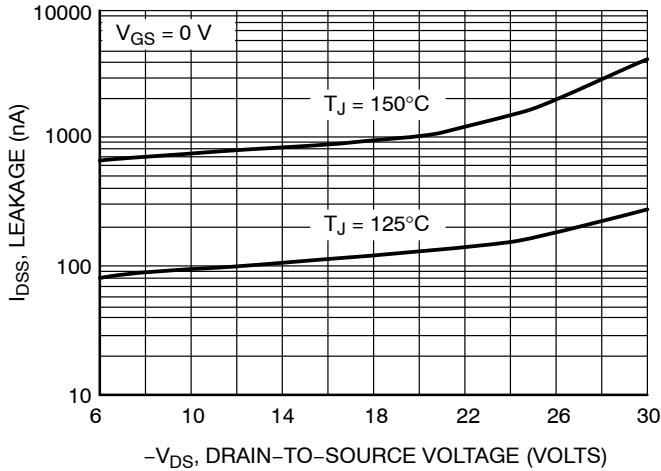


Figure 7. Drain-to-Source Leakage Current vs. Voltage

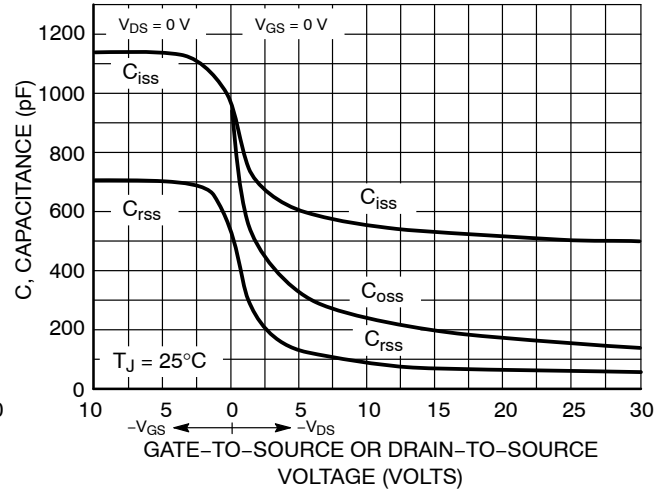


Figure 8. Capacitance Variation

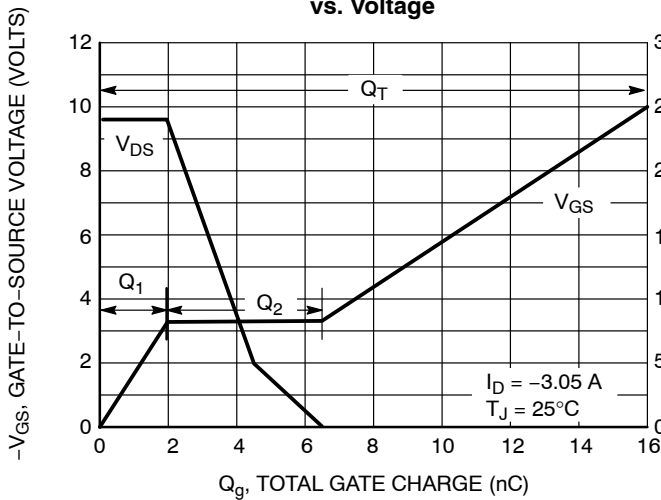


Figure 9. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

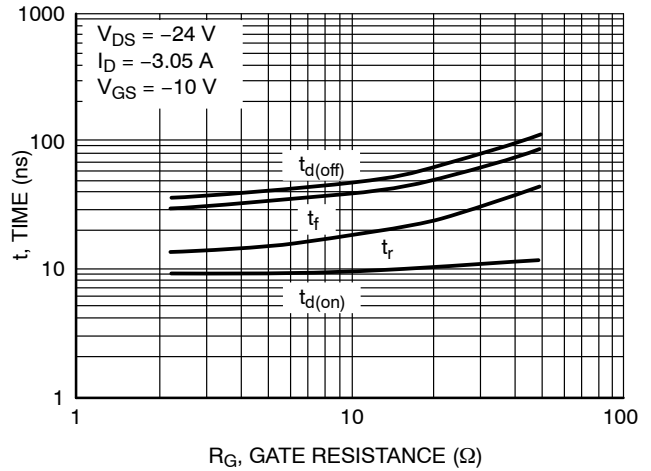


Figure 10. Resistive Switching Time Variation vs. Gate Resistance

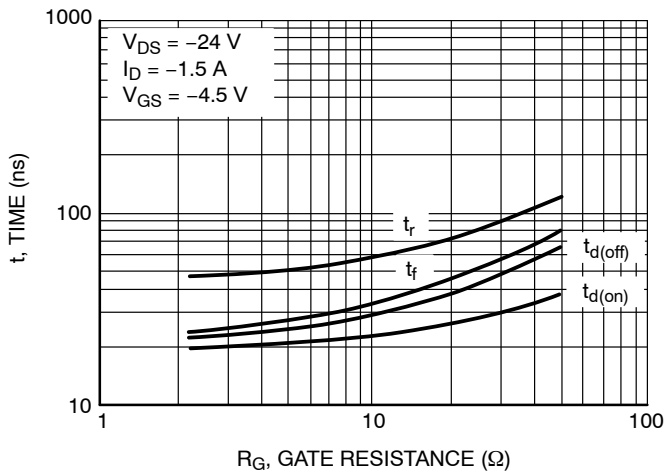


Figure 11. Resistive Switching Time Variation vs. Gate Resistance

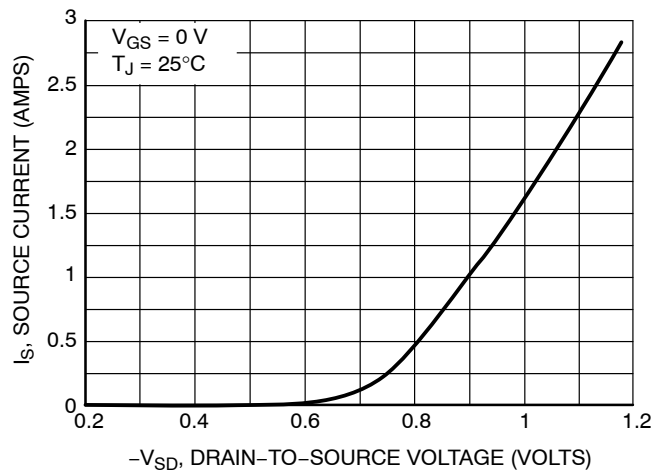


Figure 12. Diode Forward Voltage vs. Current

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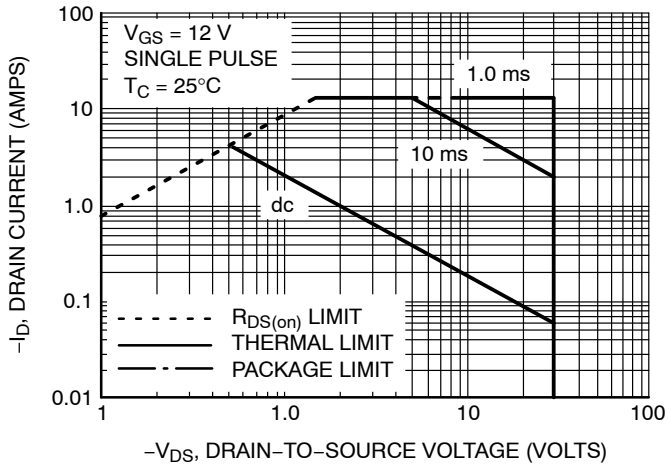


Figure 13. Maximum Rated Forward Biased Safe Operating Area

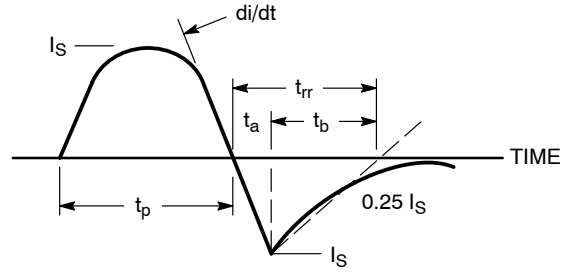


Figure 14. Diode Reverse Recovery Waveform

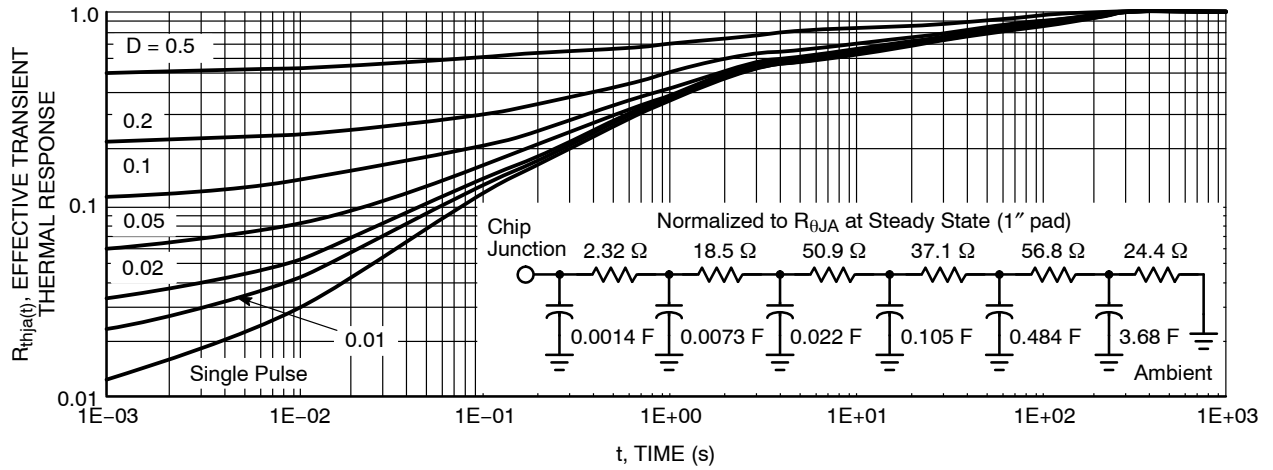


Figure 15. FET Thermal Response

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